AMENDMENTS TO THE CLAIMS

1. (Original) An adhesive film obtainable by irradiating electron beam on a molded article obtainable by molding a resin composition comprising component (A) and component (B) below:

component (A): an epoxy group-containing copolymer obtainable by polymerizing monomer (a₁) and monomer (a₂) below:

monomer (a₁): ethylene and/or propylene

monomer (a₂): a monomer represented by formula (1) below:

$$R \xrightarrow{X} O \xrightarrow{CH_2} CH \xrightarrow{CH_2} (1)$$

(wherein R represents a aliphatic hydrocarbon group of a carbon number of from 2 to 18 having a double bond, at least one of hydrogen atoms of the aliphatic hydrocarbon group may be substituted with a halogen atom, a hydroxyl group or a carboxyl group, and X represents a single bond or a carbonyl group); and

component (B): a copolymer obtainable by polymerizing monomer (b_1) and monomer (b_2) below:

monomer (b_1) : ethylene and/or propylene

monomer (b₂): α , β -unsaturated carboxylic acid anhydride.

2. (Original) The adhesive film according to claim 1, wherein the epoxy-containing copolymer of the component (A) is a melt-kneaded material.

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3. (Original) The adhesive film according to claim 1 or 2, wherein the ratio by weight of component (A) to component (B) in the resin composition ((A)/(B)) is from 100/20 to 100/50.

- 4. (Original) The adhesive film according to claim 1, wherein component (B) is a copolymer obtainable by polymerizing monomer (b_1) , monomer (b_2) and at least one selected from vinyl ester and an α , β -unsaturated carboxylic acid ester.
- 5. (Original) The adhesive film according to claim 1, wherein the ring-opening rate of the acid anhydride group derived from monomer (b₂) in component (B) is 1 to 50%, wherein the ring-opening rate of the acid anhydride is calculated by formula:

light absorbance [1] / light absorbance [2] \times 100 (%), in which light absorbance [1] is a light absorbance measured at 1850 cm⁻¹ of sample (1) with a thickness of 50 μ m, obtained by heating component (B) at 150 °C for 2 minutes at normal pressure and then heating it again at 150 °C for 2 minutes under a pressurized pressure of 50 kg/cm², and light absorbance [2] is a light absorbance measured at 1850 cm⁻¹ of sample (2) with a thickness of 50 μ m, obtained by heating the component (B) at 230 °C for 2 minutes at normal pressure and then heating it again at 230 °C for 2 minutes under a pressurized pressure of 50 kg/cm².

- 6. (Currently amended) The adhesive film according to claim 1, wherein the resin composition further contains an antioxidant. -(C).
- 7. (Original) The adhesive film according to claim 1, wherein the molded article is an article obtained by extrusion-molding.
- 8. (Original) The adhesive film according to claim 1, wherein the acceleration voltage of the electron beam is 50 to 300 kV.

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9. (Original) The adhesive film according to claim 1, wherein the irradiation dose of the electron beam is 10 to 300 kGy.

- 10. (Original) A storage method of the adhesive film according to claim 1, wherein the adhesive film is preserved at a temperature of -10°C or lower.
- 11. (Original) A laminate obtainable by laminating the adhesive film according to claim1 on an adherent and thermally curing the adhesive film.